



FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE  
(Rev. 2-32) PATENT AND TRADEMARK OFFICE

INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT

(Use several sheets if necessary)

ATTY. DOCKET NO.  
BSA 03-01

SERIAL NO.  
10/622,843

APPLICANT  
Wiesmann, et al.

CONFIRMATION NO.  
4758

FILING DATE  
July 18, 2003

GROUP  
1763

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
BT		5,231,074	July 27, 1993	Cima et al.			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

BT		1. Author: Chan et al.; Title: "Effect of the Post-Deposition Processing Ambient on the Preparation of Superconducting $YBa_2Cu_3O_{7-x}$ Coevaporated Thin Films Using a $BaF_2$ Source;" Publication: <i>Appl. Phys. Lett.</i> 53(15): 1443-1445; Date of Publication: October 1988.
		2. Author: Solovyov et al.; Title: "Ex-situ Post-deposition Processing for Large Area $YBa_2Cu_3O_7$ Films and Coated Tapes;" Publication: <i>IEEE Transactions on Applied Superconductivity</i> 11(1):2939-2942; Date of Publication: March 2001.
		3. Author: Solovyov et al.; Title: "Thick $YBa_2Cu_3O_7$ Films by Post Annealing of the Precursor by High Rate E-beam Deposition on $SrTiO_3$ Substrates;" <i>Physica C</i> 309: 269-274; Date of Publication: December 1998.
		4. Author: Solovyov et al.; Title: "High Rate Deposition of 5 Micron Thick $YBa_2Cu_3O_7$ Films using the $BaF_2$ Ex-Situ Post Annealing Process;" Publication: <i>IEEE Transactions on Applied Superconductivity</i> 9(2):1467-1470; Date of Publication: June 1999.
		5. Author: Solovyov et al.; Title: "Growth rate limiting mechanisms of $YBa_2Cu_3O_7$ films manufactured by ex situ processing;" Publication: <i>Physica C</i> 353:14-22; Date of Publication: 2001.
		6. U.S. Application Publication No. 2003/0050195.

EXAMINER

BT/ta/bjt

DATE CONSIDERED

9/12/05

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication with applicant.